

In re application: Jun Zheng
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AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning at page 7, line 17, with the following rewritten paragraph:

AI 5 --Array 200 comprises a plurality of layers, including substrate 202 mounted on submount 201, bottom DBR layer 203 disposed on substrate 202, active region layer 204 disposed on bottom DBR layer 203, and heat-spreading layer 207 disposed on active region layer 204. The device of claim 8, further comprising an active region layer 204 comprising includes the active region 214 and active region layer portions outside the active region 214, wherein the heat-spreading layer is disposed on the top surface of the active region and on a top surface of the active region layer portions outside the active region. Heat-spreading layer 207 thus is directly disposed on the top surface of active region 214, and also on other material of the array outside the VCSEL active region 214 itself, namely on the top surface of portions of the active region layer 204 outside the active region 214. Thus, heat-spreading layer can receive and remove heat from the top of active region 214, and carry it to other material of the array outside the VCSEL 210 and active region 214.--

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